

The Institute of Electrical and Electronics Engineers, Inc.

Components, Packaging and Manufacturing Technology Society Orange County Chapter

Presents an All-Day Workshop on **3D Integrated Circuits: Technologies Enabling the Revolution**

Date & Time: **Friday, December 9, 2011 – 9:00am to 4:00pm**Location: **Jazz Semiconductor Auditorium,**[Conexant Systems, Inc. 4321 Jamboree Road, Newport Beach, CA 92660](http://www.conexant.com)

This one-day topical workshop will provide a comprehensive examination of the technologies, materials, manufacturing processes, equipment, advances in test methodology, and design tools that are enabling three-dimensional integrated circuits (3DICs). The remarkable progress in the electronics industry has been driven by technology advancements in semiconductors. Continued technology advancement driven by the relentless needs for lower cost, higher performance, lower power, and longer battery life in electronic devices has resulted in the requirement for 3D integration. Although there has been significant progress in development of 3D technologies it has not yet reached the high volume production mainstream. Join us for a unique one-day workshop that brings together experts from design, manufacturing, test, and materials to discuss the promise and technologies for 3D IC.

Featured Speakers

Dr. Phil Garrou

Microelectronic Consultants of North Carolina

Dr. Norman Chang

Co-Founder, Apache Design Solutions, Ansys

Dr. Eric Beyne

Scientific Director, Adv. Pkg and Interconnect, IMEC

Ted Tessier

Chief Technical Officer, Flip Chip International

Dr. GS Kim

CEO & Founder, EPWorks, Seoul, Korea

Dr. Suresh Ramalingam

Sr. Director, Advanced Package Design & Development, Xilinx

Dr. Rose Guino, Dr. Betty Huang, Dr. Kevin Becker

Henkel Electronics Materials LLC.

Dr. Muhannad Bakir

Georgia Tech – Integrated 3D Systems Group

Dr. Yeong Lee

Director, STATS ChipPAC

Dr. Steve Pateras

Product Marketing Director, Silicon Test, Mentor Graphics

Vendor Exhibits and Sponsor Displays!

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Registrations:

Early-Bird Registration Fees: IEEE Members - \$40; Non-Members of IEEE - \$50; Students - \$20

Prices will go up by \$20 for each category, after Nov 25, 2011.

Registration Instructions at http://meetings.vtools.ieee.org/meeting_view/list_meeting/8019

Workshop Organizing Committee

General ChairDr. Lawrence Williams, ANSYS Corporation, l.williams@ieee.org**Technical Program**Dr. Donald Frye, Henkel Electronics Materials LLC, don3569@yahoo.comRobert Warren, Conexant Systems, Inc. Robert.Warren@conexant.comSam Karikalan, Broadcom Corporation, samkarikalan@ieee.org**Vendor Exhibits:**Mark Kuhlman, Semtech Corporation, Mkuhlman@semtech.com**Publicity & Local Arrangements:**Jaydutt Joshi, Skyworks Solutions, Inc., jaydutt@gmail.comAaron Edwards, ANSYS Corporation, aaron.edwards@ansys.com**University Relations:**Prof. Mark Bachman, Univ. of California – Irvine, mbachman@uci.edu**Registration & Finances:**Melissa Lau, Broadcom Corporation, melissa@broadcom.com